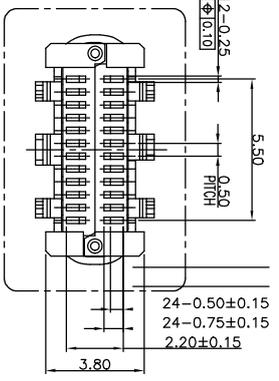
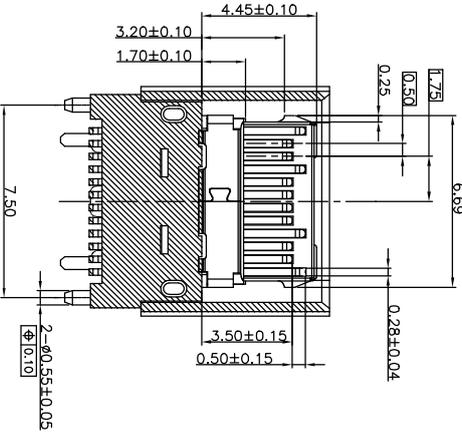
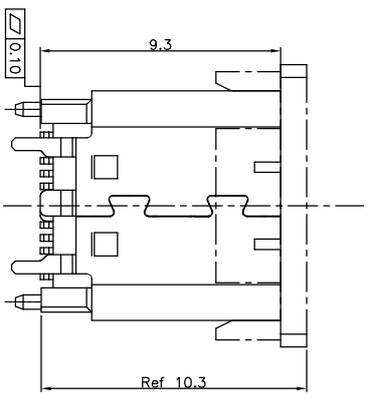
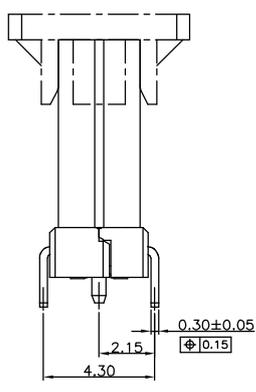
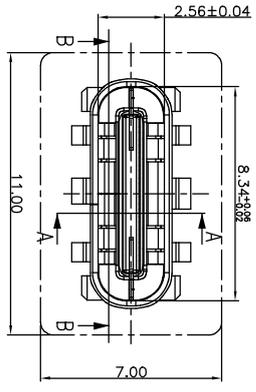
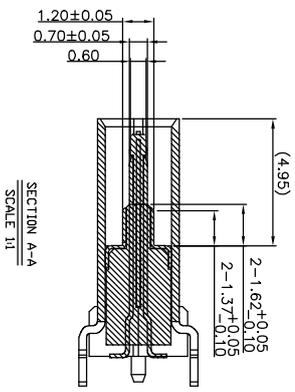
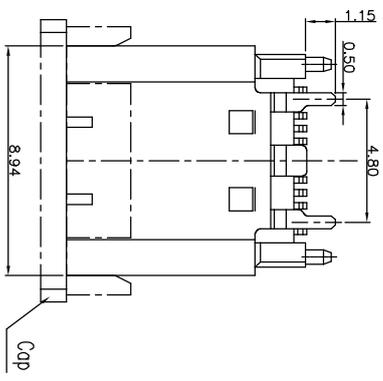
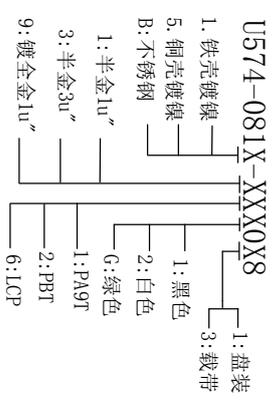


REV.	ECN NO.	APPD.
A0	/	/



NOTES:

1. MATERIAL:
MOLDING: LCP U194 V-0
CONTACT: COPPER ALLOY.
GOLD PLATING ALL OVER 50u" Min NICKEL
AND 100u" Min Tin ALL OVER 50u" Min NICKEL
ON SOLDER AREA
SHELL: SUS304-H,T=0.30±0.03mm
50u" NICKEL PLATING OVER ALL.
SHILD: SUS304-H,T=0.12±0.03mm
2. MECHANICAL:
INSERTION: 5~20N.
EXTRACTION: 8~20N.
DURABILITY: 10000 CYCLES
3. ELECTRICAL:
CURRENT: 5A MIN FOR VBUS;
0.25A MIN FOR OTHER.
V LTAGE: 20 V MAX
WITHSTANDING VOLTAGE: 100V AC.
CONTACT RESISTANCE: 40mΩ MAX.
INSULATION RESISTANCE: 100MΩ MIN.
4. ENVIR NMENTAL
TEMPERATURE RANGE -55°C ~ +85°C



U574-081X-XXXXX8

TOLERANCE UNLESS OTHERWISE SPECIFIED	XXX ±0.10	XX ±0.20	X ±0.30	X' ±3	XX' ±2
HUA LIAN WEI TECHNOLOGY ELECTRONICS CO.,LTD.					

深圳市华联威电子科技有限公司

TYPE C 180度立贴式9.3 H款

APPROVED	PART NAME:	TYPE C 180度立贴式9.3 H款
CHECKED	PART NO:	U574-081X-XXX038
DRAWN	PROJECTION:	UNIT: SCALE SHEET REV.
DATE	mm	1:1 10F1 A0